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03/06/02

U.S. UTILITY Patent Application

PATENT NUMBER and
ISSUE DATE

APPL NUM	FILING DATE	CLASS	SUBCLASS	GAU	EXAMINER
10092890	03/06/2002	25758	455	2684	V. YEVSIKOV

**APPLICANTS: Lutz Markus;

**CONTINUING DATA VERIFIED:

** FOREIGN APPLICATIONS VERIFIED:

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PG-PUB DO NOT PUBLISH ☐RESCIND ☐Foreign priority claimed ☐ yes ☐ no35 USC 119 conditions met ☐ yes ☐ no

Verified and Acknowledged Examiners's initials

ATTORNEY DOCKET NO

11403/13

TITLE : Si wafer-cap/wafer bonding method using local laser energy, device produced by the method, and system used in the method

U.S. DEPT. OF COMM./PAT. & TM.-PTO-436L (Rev. 12-94)

NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
		Total Claims	Print Claim for O.G.
ISSUE FEE		DRAWING	
Amount Due	Date Paid	Sheets Drwg.	Figs. Drwg. Print Fig.
		Application Examiner	
<input type="checkbox"/> TERMINAL DISCLAIMER		PREPARED FOR ISSUE	
		WARNING: The information disclosed herein may be restricted. Unauthorized disclosure may be prohibited by the United States Code Title 35, Sections 122, 181 and 368, Possession outside the U.S. Patent & Trademark Office is restricted to authorized employees and contractors only.	

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